

## Trench gate field-stop IGBT, 650 V, 50 A soft switching IH series in a TO-247 long leads package

Datasheet - production data

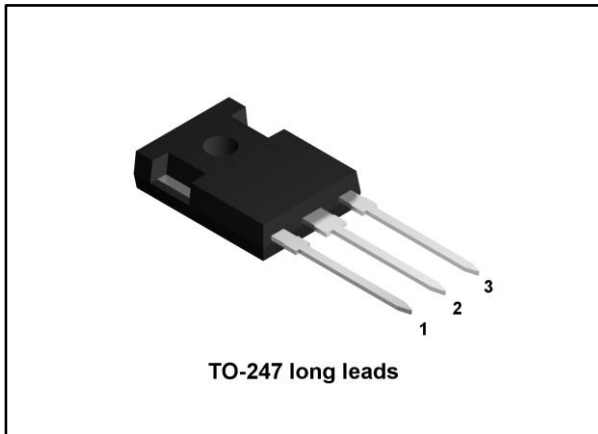
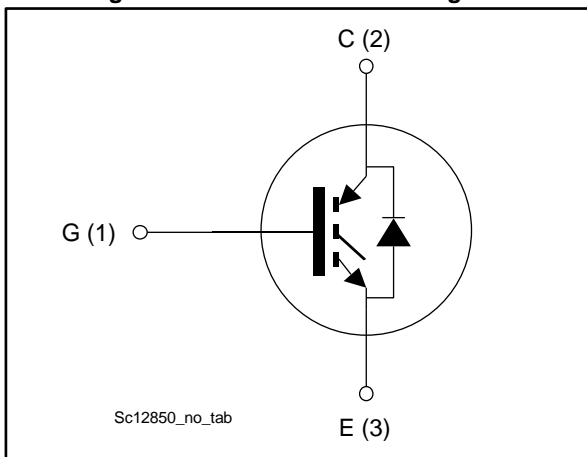


Figure 1: Internal schematic diagram



### Features

- Designed for soft-commutation only
- Maximum junction temperature:  $T_J = 175\text{ }^\circ\text{C}$
- $V_{CE(sat)} = 1.5\text{ V (typ.) @ } I_C = 50\text{ A}$
- Minimized tail current
- Tight parameter distribution
- Low thermal resistance
- Low voltage drop freewheeling co-packaged diode

### Applications

- Induction heating
- Resonant converters
- Microwave oven

### Description

The newest IGBT 650 V soft-switching IH series has been developed using an advanced proprietary trench gate field-stop structure, whose performance is optimized both in conduction and switching losses for soft-commutation. A freewheeling diode with a low drop forward voltage is included. The result is a product specifically designed to maximize efficiency for any resonant and soft-switching applications.

Table 1: Device summary

Order code	Marking	Package	Packing
STGWA50IH65DF	G50IH65DF	TO-247 long leads	Tube

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# 1 Electrical ratings

**Table 2: Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0$ V)	650	V
$I_C$	Continuous collector current at $T_C = 25$ °C	100	A
	Continuous collector current at $T_C = 100$ °C	50	
$I_{CP}^{(1)}$	Pulsed collector current	150	
$V_{GE}$	Gate-emitter voltage	$\pm 20$	V
$I_F$	Continuous forward current at $T_C = 25$ °C	50	A
	Continuous forward current at $T_C = 100$ °C	25	
$I_{FP}^{(1)}$	Pulsed forward current	150	
$P_{TOT}$	Total dissipation at $T_C = 25$ °C	300	W
$T_{STG}$	Storage temperature range	- 55 to 150	°C
$T_J$	Operating junction temperature range	- 55 to 175	

**Notes:**

<sup>(1)</sup>Pulse width limited by maximum junction temperature.

**Table 3: Thermal data**

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance junction-case IGBT	0.5	°C/W
	Thermal resistance junction-case diode	1.47	
$R_{thJA}$	Thermal resistance junction-ambient	50	

## 2 Electrical characteristics

$T_C = 25\text{ °C}$  unless otherwise specified

**Table 4: Static characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}$ , $I_C = 250\text{ }\mu\text{A}$	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}$ , $I_C = 50\text{ A}$		1.50	2.00	
		$V_{GE} = 15\text{ V}$ , $I_C = 50\text{ A}$ , $T_J = 125\text{ °C}$		1.75		
		$V_{GE} = 15\text{ V}$ , $I_C = 50\text{ A}$ , $T_J = 175\text{ °C}$		1.90		
$V_F$	Forward on-voltage	$I_F = 25\text{ A}$		1.75	2.50	
		$I_F = 25\text{ A}$ , $T_J = 125\text{ °C}$		1.50		
		$I_F = 25\text{ A}$ , $T_J = 175\text{ °C}$		1.40		
		$I_F = 50\text{ A}$		2.15		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}$ , $I_C = 1\text{ mA}$	5	6	7	
$I_{CES}$	Collector cut-off current	$V_{GE} = 0\text{ V}$ , $V_{CE} = 650\text{ V}$			25	$\mu\text{A}$
$I_{GES}$	Gate-emitter leakage current	$V_{CE} = 0\text{ V}$ , $V_{GE} = \pm 20\text{ V}$			$\pm 250$	nA

**Table 5: Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input capacitance	$V_{CE} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GE} = 0\text{ V}$	-	2980	-	pF
$C_{oes}$	Output capacitance		-	150	-	
$C_{res}$	Reverse transfer capacitance		-	81	-	
$Q_g$	Total gate charge	$V_{CC} = 520\text{ V}$ , $I_C = 50\text{ A}$ , $V_{GE} = 0\text{ to }15\text{ V}$ (see <a href="#">Figure 24: "Gate charge test circuit"</a> )	-	158	-	nC
$Q_{ge}$	Gate-emitter charge		-	25	-	
$Q_{gc}$	Gate-collector charge		-	72	-	

**Table 6: IGBT switching characteristics (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(off)}$	Turn-off-delay time	$V_{CC} = 400\text{ V}$ , $I_C = 50\text{ A}$ , $V_{GE} = 15\text{ V}$ , $R_G = 22\text{ }\Omega$ (see <a href="#">Figure 22: "Test circuit for inductive load switching"</a> )	-	260	-	ns
$t_f$	Current fall time		-	17	-	
$t_{d(off)}$	Turn-off-delay time	$V_{CC} = 400\text{ V}$ , $I_C = 50\text{ A}$ , $V_{GE} = 15\text{ V}$ , $R_G = 22\text{ }\Omega$ , $T_J = 175\text{ °C}$ (see <a href="#">Figure 22: "Test circuit for inductive load switching"</a> )	-	270	-	ns
$t_f$	Current fall time		-	24	-	

Table 7: IGBT switching characteristics (snubbed inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$E_{off}^{(1)}$	Turn-off switching energy	$V_{CC} = 320 \text{ V}$ , $R_G = 10 \text{ } \Omega$ , $I_C = 50 \text{ A}$ , $L = 100 \text{ } \mu\text{H}$ , $C_{snub} = 22 \text{ nF}$ (see <a href="#">Figure 23: "Test circuit for capacitive load switching"</a> )	-	284	-	$\mu\text{J}$
		$V_{CC} = 320 \text{ V}$ , $R_G = 10 \text{ } \Omega$ , $I_C = 50 \text{ A}$ , $L = 100 \text{ } \mu\text{H}$ , $C_{snub} = 22 \text{ nF}$ $T_J = 175 \text{ } ^\circ\text{C}$ (see <a href="#">Figure 23: "Test circuit for capacitive load switching"</a> )	-	469	-	

**Notes:**

<sup>(1)</sup>Including the tail of the collector current.

### 2.1 Electrical characteristics (curves)

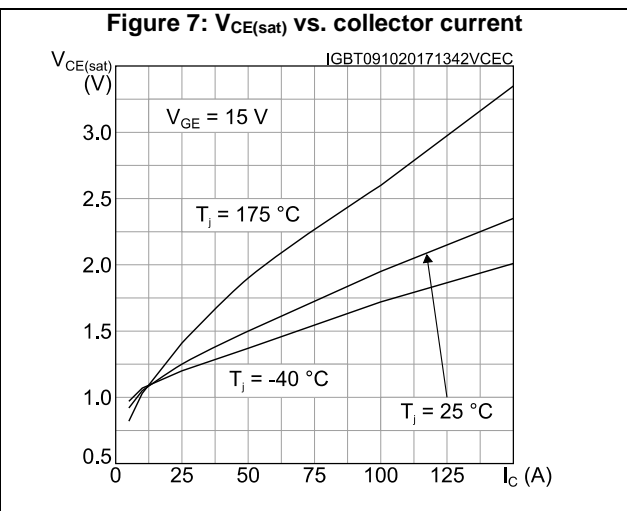
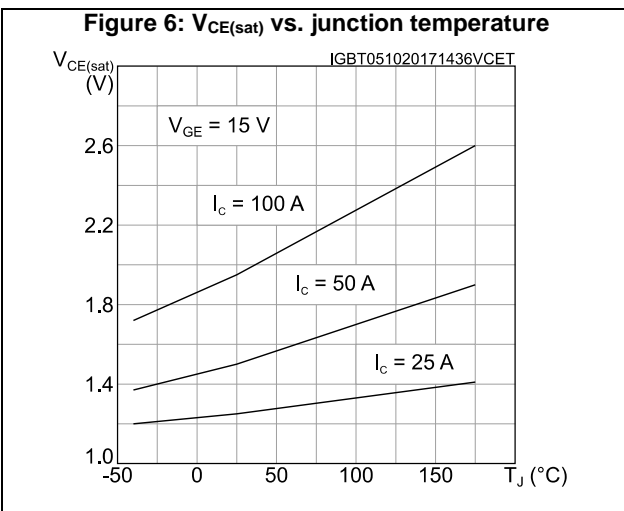
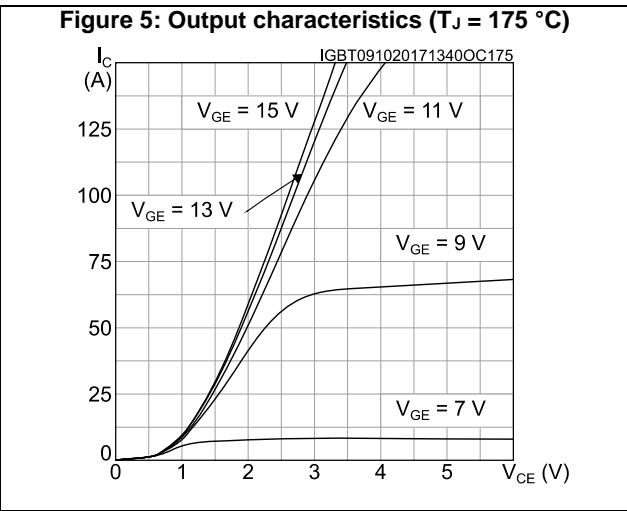
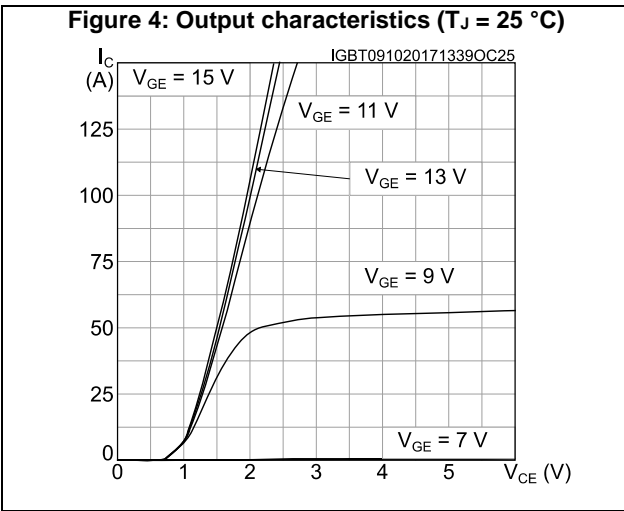
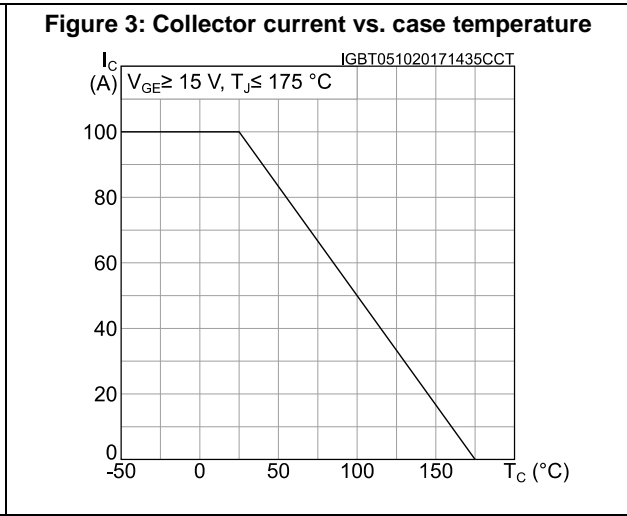
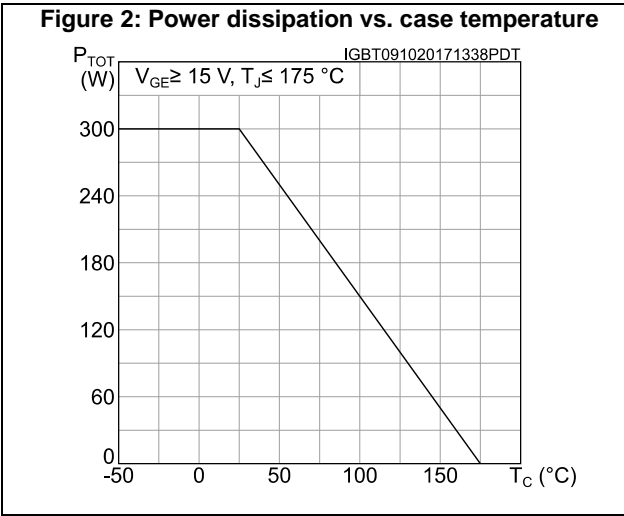


Figure 8: Forward bias safe operating area

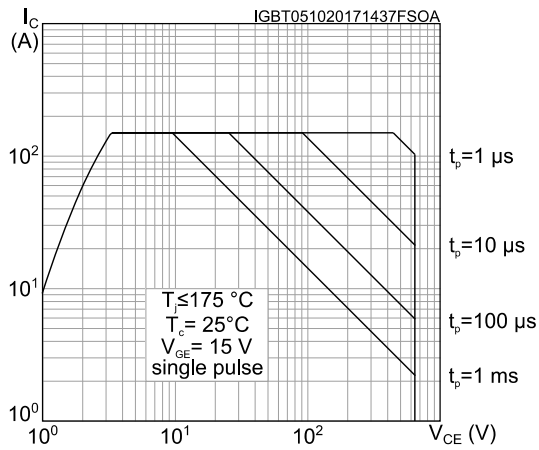


Figure 9: Transfer characteristics

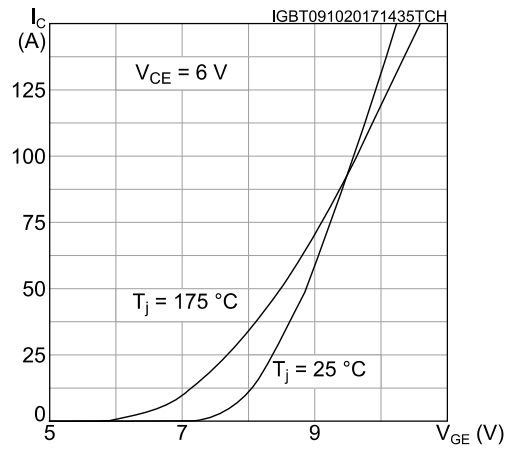


Figure 10: Diode V\_F vs. forward current

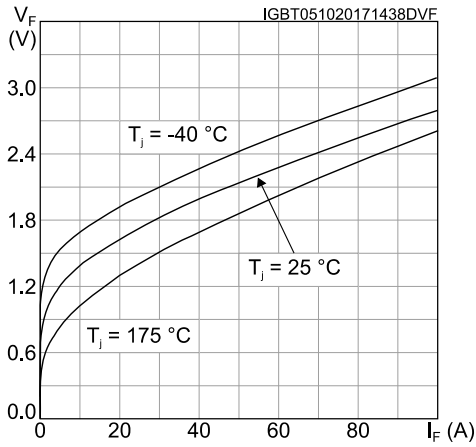


Figure 11: Normalized V\_GE(th) vs. junction temperature

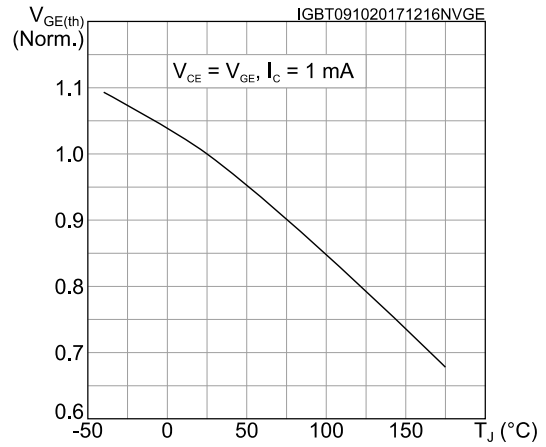


Figure 12: Normalized V\_(BR)CES vs. junction temperature

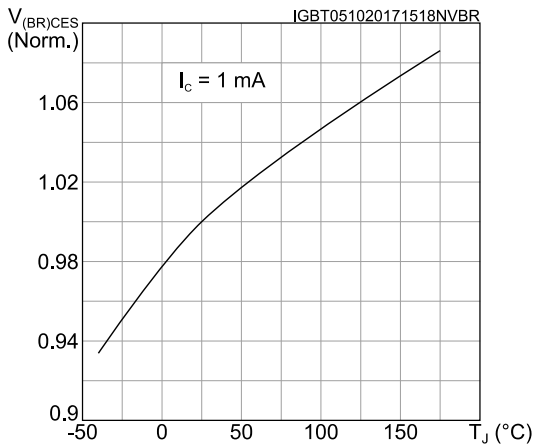
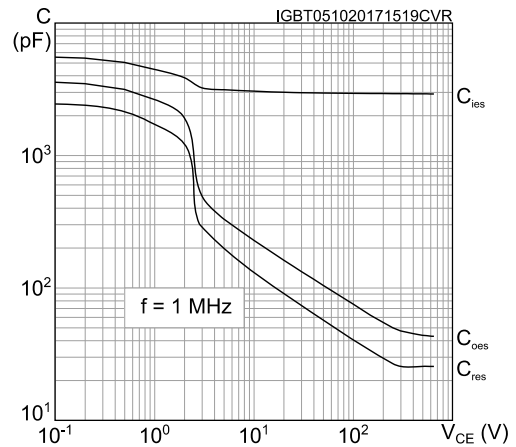


Figure 13: Capacitance variations



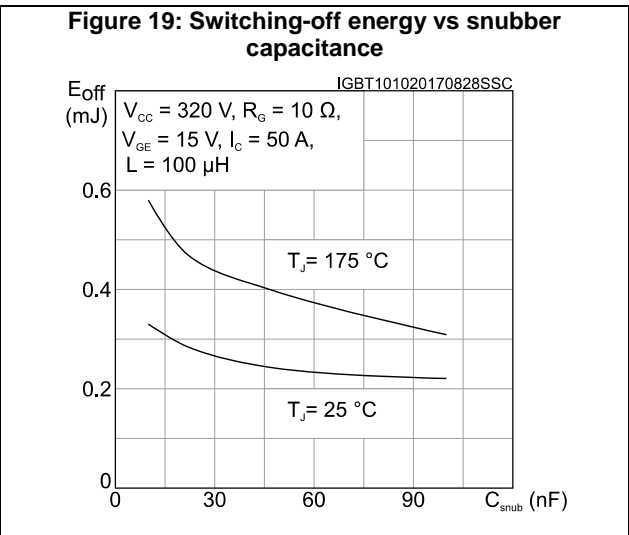
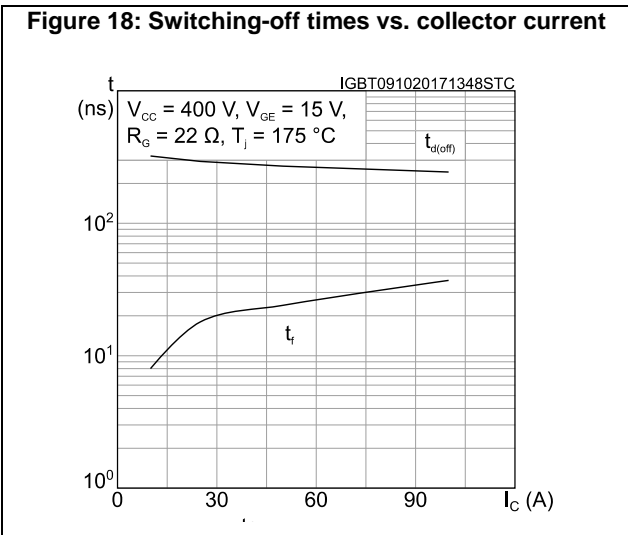
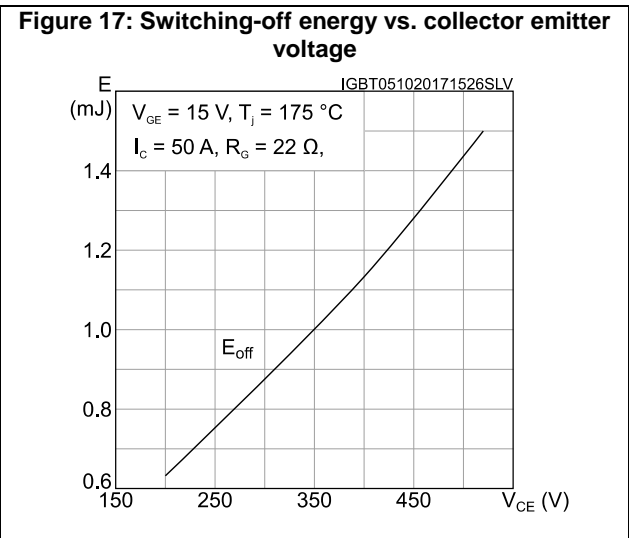
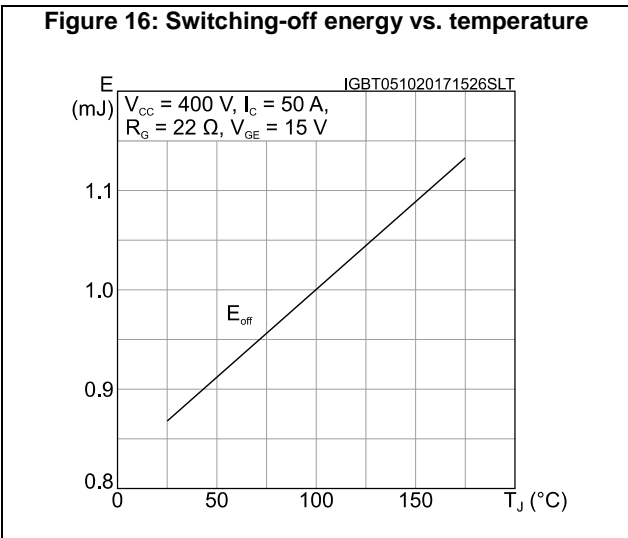
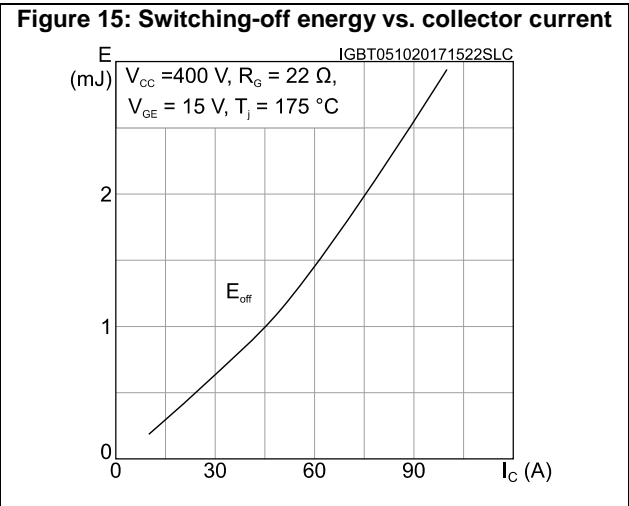
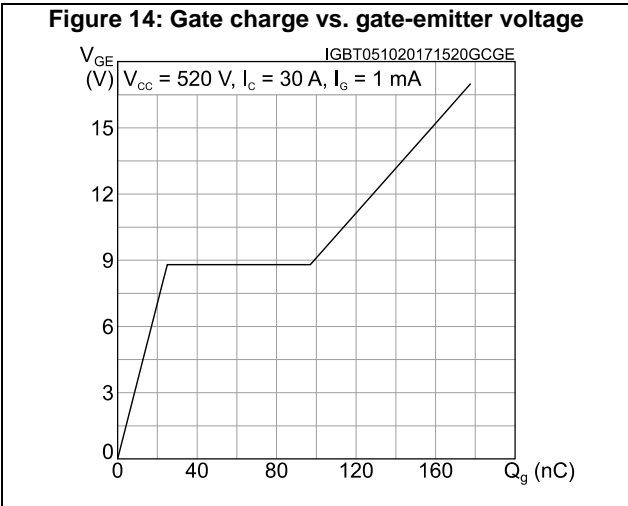




Figure 20: Thermal impedance

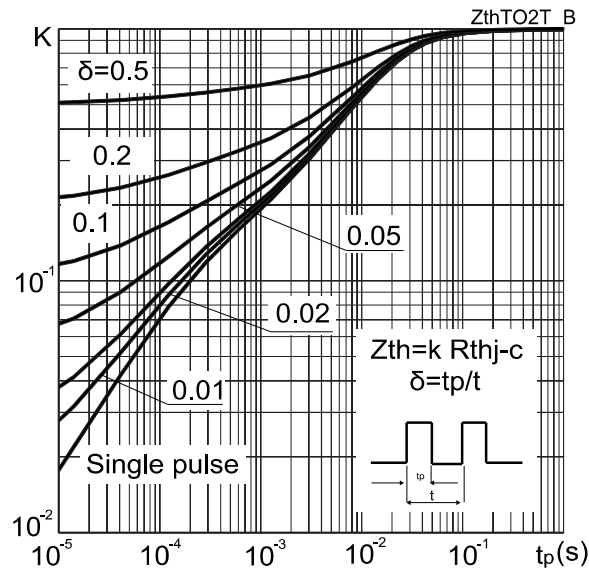
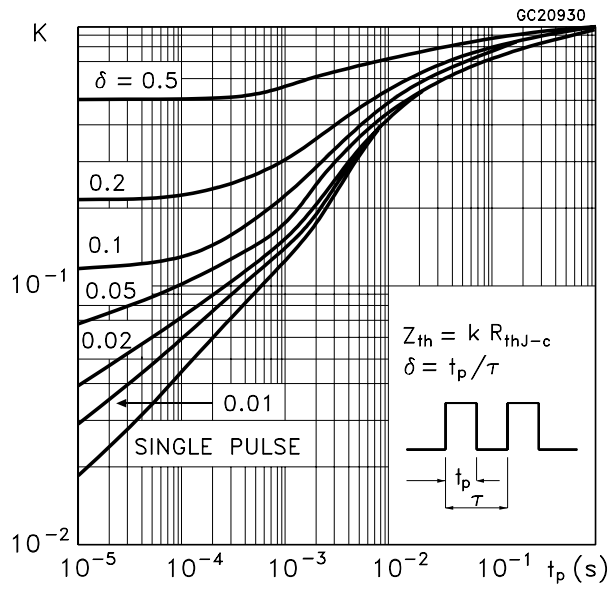
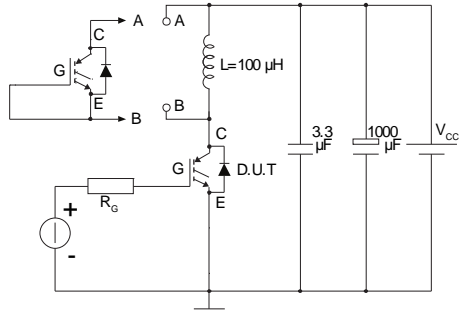


Figure 21: Thermal impedance for diode



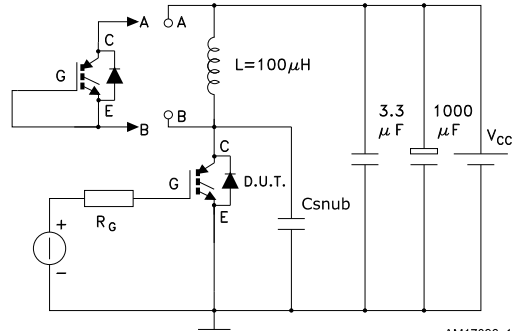
### 3 Test circuits

Figure 22: Test circuit for inductive load switching



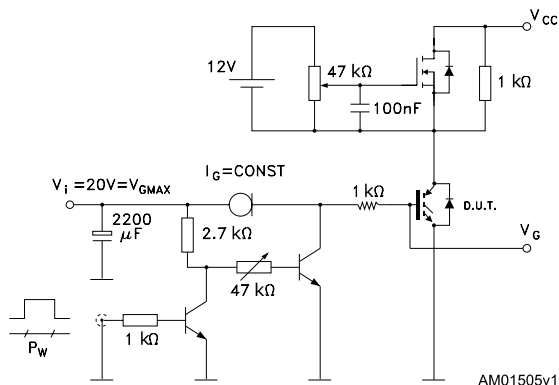
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Figure 23: Test circuit for snubbed inductive load switching



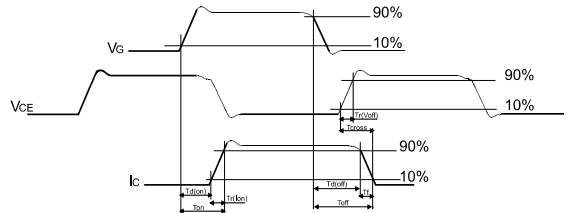
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Figure 24: Gate charge test circuit



AM01505v1

Figure 25: Switching waveform



AM01506v1

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 TO-247 long leads package information

Figure 26: TO-247 long leads package outline

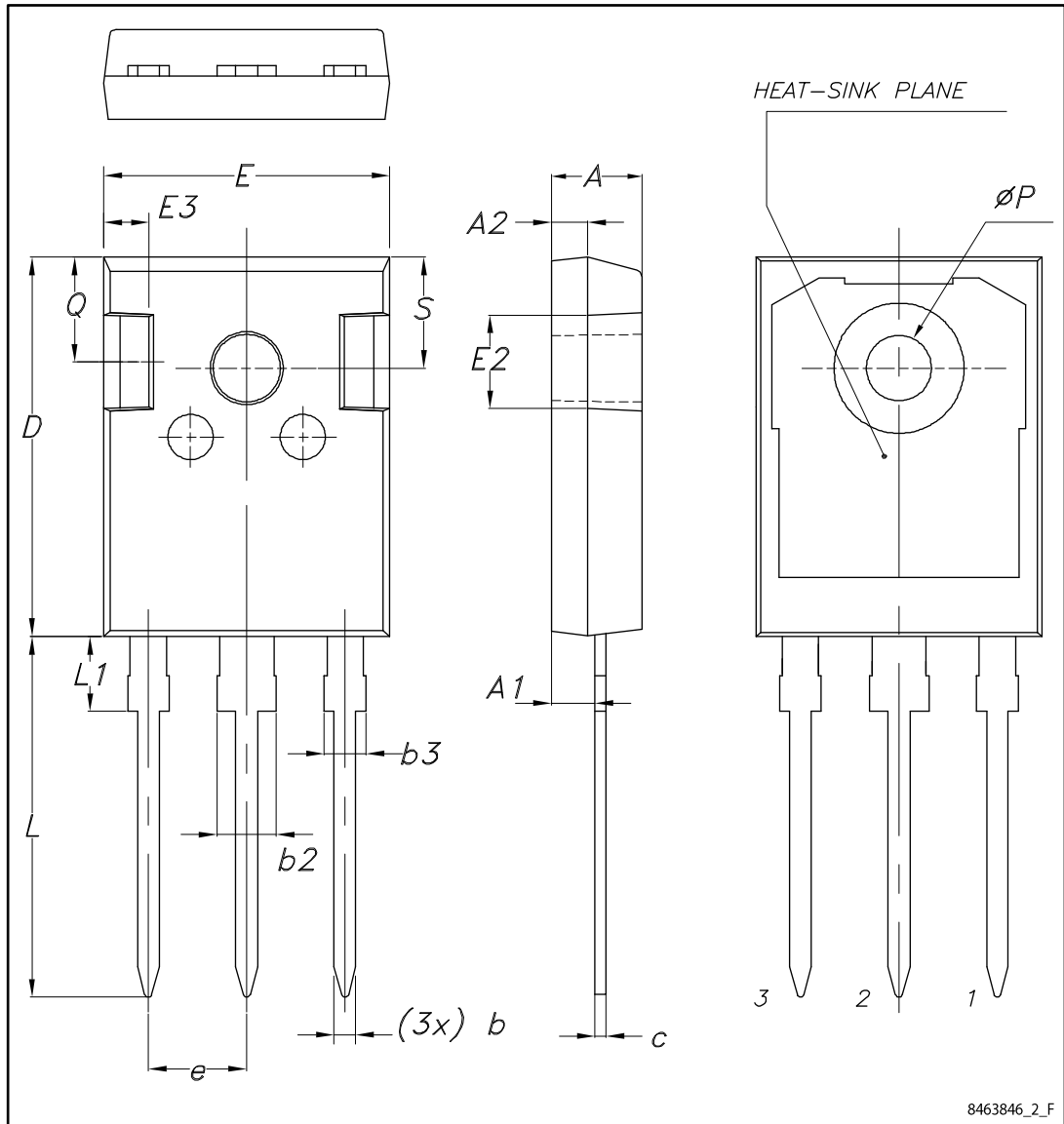


Table 8: TO-247 long leads package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
b	1.16		1.26
b2			3.25
b3			2.25
c	0.59		0.66
D	20.90	21.00	21.10
E	15.70	15.80	15.90
E2	4.90	5.00	5.10
E3	2.40	2.50	2.60
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1			4.30
P	3.50	3.60	3.70
Q	5.60		6.00
S	6.05	6.15	6.25

## 5 Revision history

**Table 9: Document revision history**

Date	Revision	Changes
02-Sep-2016	1	First release.
05-Oct-2017	2	Modified title, silhouette, features and description. Modified <a href="#">Table 2: "Absolute maximum ratings"</a> , <a href="#">Table 3: "Thermal data"</a> , <a href="#">Table 4: "Static characteristics"</a> , <a href="#">Table 5: "Dynamic characteristics"</a> , <a href="#">Table 6: "IGBT switching characteristics (inductive load)"</a> and <a href="#">Table 7: "IGBT switching characteristics (snubbed inductive load)"</a> . Added <a href="#">Section 2.1: "Electrical characteristics (curves)"</a> . Minor text changes.

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